



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Michael B. Ball

Serial No.: 08/602,503

Filed: February 20, 1996

For: METHOD OF FABRICATING A
MULTI-DIE SEMICONDUCTOR
PACKAGE ASSEMBLY (as amended)

Confirmation No.: 4539

Examiner: Dilinh P. Nguyen

Group Art Unit: 2814

Attorney Docket No.: 2269-2718.4US
(95-0837.04/US)

Notice of Allowance Mailed:

April 21, 2006

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EV669816545US

Date of Deposit with USPS: July 21, 2006

Person making Deposit: Wendy Neff

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the specification begin on page 3 of this paper;

Amendments to the Abstract appear on page 10 of this paper;

A listing of the claims begins on page 11 of this paper;

Corrections to the drawings are summarized on page 15 of this paper, with replacement sheets and annotated sheets showing the corrections enclosed herewith; and

Remarks start at page 16 of this paper.